Subcontract Wafer Services
Full Turnkey Wafer Processing Services

Wafer Mapping / Wafer Inking
- Conversion between industry formats
- Inking using any electronic wafer map

Wafer Thinning
- Automated in-feed grinding of wafers
- Ability to saw, sort and inspect wafers down to 20 µ

Wafer Dicing
- ±1 µ tolerance
- Wafer sizes up to 12 in. / 300 mm
- Custom dicing plans, multi-project wafers, step cutting & yield optimizations

Die Plating / Pick & Place
- Automated, virtually contactless handling of singulated die
- Compatible with all electronic wafer maps
- Multiple bin / grade die picking
- Safe handling of sensitive topside & 3D features

Visual Inspection
- AQL
- MIL-STD (commercial, military and aerospace grades)
- Custom visual
- Inspection via AOI equipment available

Customized Output
- Sawn wafer on film-frame and ring-frame
- Waffle tray or Gel-Pak
- Reconstructed wafer
- Tape-and-reel (pocket, blister or SurfTape®)

High volume capacity
Low volume flexibility for developments and R&D
35+ years processing experience

Quality Certifications
AS9100 Rev. C
ISO9001:2008

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Micross Components, a leading global provider of distributed and specialty electronic components for aerospace, military, defense and other demanding applications, has operated as a single-source provider of high reliability, state-of-the-art electronics for 35+ years. Micross’ solutions range from bare die and wafer processing through advanced and custom packaging to leading edge component design and test. Micross possesses the design, manufacturing, testing and logistics expertise needed to support an application from start to finish.